

•USP-6B04 Power Dissipation

Power dissipation data for the USP-6B04 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board Dimensions: 40mmx40mm (1600mm² in one side)

1st Inner Metal Layer about 50%

2nd Inner Metal Layer about 50%

3rd Inner Metal Layer about 50%

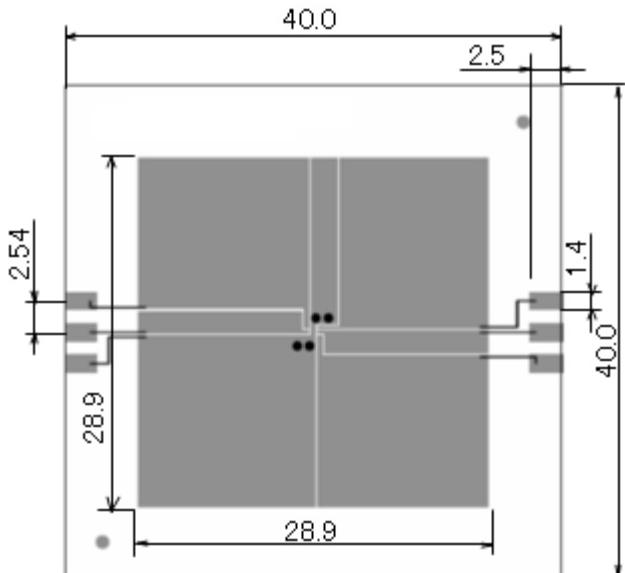
4th Inner Metal Layer about 50%

Each heat sink back metal is connected to the
Inner layers respectively.

Material: Glass Epoxy (FR-4)

Thickness: 1.0 mm

Through-hole: 4 x 0.4 Diameter



Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient temperature

Board Mount (Tjmax=125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	600	166.67
85	240	

